

## General Description

Renesas SLG7RN46351 is a low power and small form device. The SoC is housed in a 2mm x 3mm STQFN package which is optimal for using with small devices.

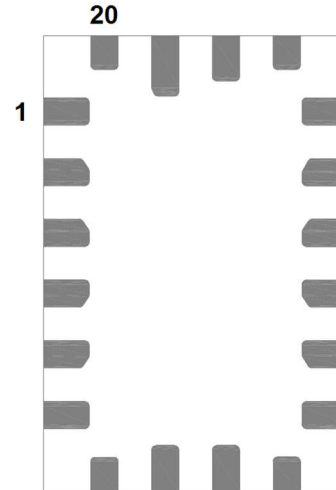
## Features

- Low Power Consumption
- Pb - Free / RoHS Compliant
- Halogen - Free
- STQFN - 20 Package

## Output Summary

15 Outputs - Push Pull 2X

## Pin Configuration

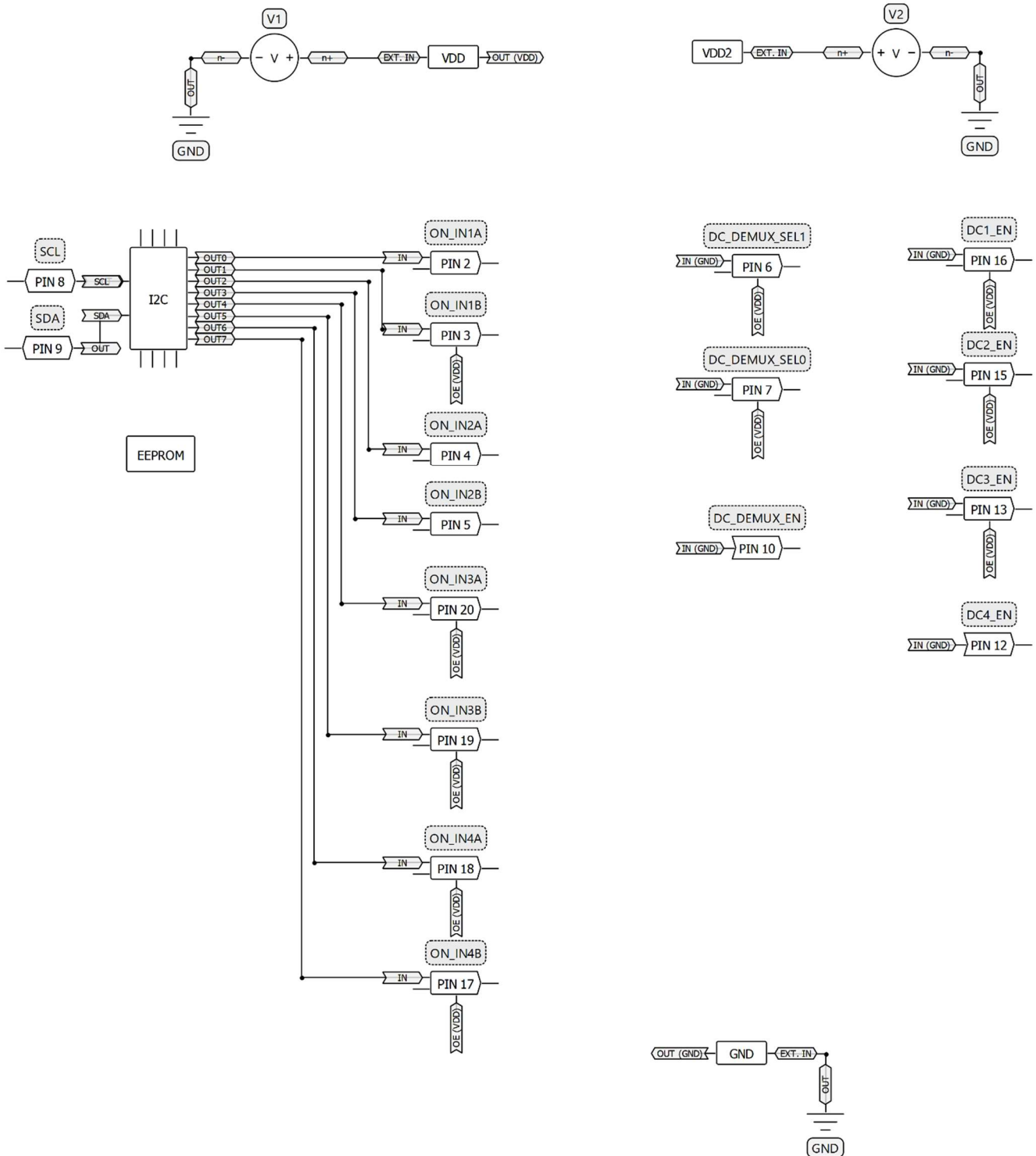


20-pin STQFN  
(Top View)

## Pin name

Pin #	Pin name	Pin #	Pin name
1	VDD	11	GND
2	ON_IN1A	12	DC4_EN
3	ON_IN1B	13	DC3_EN
4	ON_IN2A	14	VDD2
5	ON_IN2B	15	DC2_EN
6	DC_DEMUX_SEL1	16	DC1_EN
7	DC_DEMUX_SEL0	17	ON_IN4B
8	SCL	18	ON_IN4A
9	SDA	19	ON_IN3B
10	DC_DEMUX_EN	20	ON_IN3A

#### Block Diagram



### Pin Configuration

Pin #	Pin Name	Type	Pin Description	Internal Resistor
1	VDD	PWR	Supply Voltage	--
2	ON_IN1A	Digital Output	Push Pull 2X	floating
3	ON_IN1B	Digital Output	Push Pull 2X	floating
4	ON_IN2A	Digital Output	Push Pull 2X	floating
5	ON_IN2B	Digital Output	Push Pull 2X	floating
6	DC_DEMUX_SEL1	Digital Output	Push Pull 2X	floating
7	DC_DEMUX_SEL0	Digital Output	Push Pull 2X	floating
8	SCL	Digital Input	Low Voltage Digital Input	floating
9	SDA	Digital Input	Low Voltage Digital Input	floating
10	DC_DEMUX_EN	Digital Output	Push Pull 2X	floating
11	GND	GND	Ground	--
12	DC4_EN	Digital Output	Push Pull 2X	floating
13	DC3_EN	Digital Output	Push Pull 2X	floating
14	VDD2	PWR	Supply Voltage	--
15	DC2_EN	Digital Output	Push Pull 2X	floating
16	DC1_EN	Digital Output	Push Pull 2X	floating
17	ON_IN4B	Digital Output	Push Pull 2X	floating
18	ON_IN4A	Digital Output	Push Pull 2X	floating
19	ON_IN3B	Digital Output	Push Pull 2X	floating
20	ON_IN3A	Digital Output	Push Pull 2X	floating

### Ordering Information

Part Number	Package Type
SLG7RN46351V	20-pin STQFN
SLG7RN46351V	20-pin STQFN - Tape and Reel (3k units)

### Absolute Maximum Conditions

Parameter	Min.	Max.	Unit
$V_{HIGH}$ to GND	-0.3	7	V
Voltage at Input Pin	GND-0.5V	VDD+0.5V	V
Maximum Average or DC Current Through $V_{DD}$ Pin	--	90	mA
Maximum Average or DC Current Through $V_{DD2}$ Pin	--	90	mA
Maximum Average or DC Current Through GND Pin (Per chip side, (Note 1))	--	100	mA
Maximum Average or DC Current (Through pin)	Push-Pull 2x		mA
Current at Input Pin	-1.0	1.0	mA
Input leakage (Absolute Value)	--	1000	nA
Storage Temperature Range	-65	150	°C
Junction Temperature	--	150	°C
ESD Protection (Human Body Model)	2000	--	V
ESD Protection (Charged Device Model)	1300	--	V
Moisture Sensitivity Level	1		

Note 1 The GreenPAK's GND rail is divided in two sides. IOs 0 to 6, SCL, SDA are connected to one side and IOs 7 to 14 are connected to another side.

### Electrical Characteristics

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
$V_{DD}$	Supply Voltage		2.4	3.3	5	V
$V_{DD2}$	Supply Voltage		1.71	3.3	5	V
$T_A$	Operating Temperature		-40	25	85	°C
$C_{VDD}$	Capacitor Value at VDD		--	0.1	--	µF
$C_{IN}$	Input Capacitance		--	4	--	pF
$I_Q$	Quiescent Current	VDD=5V; SCL and SDA HIGH; Floating outputs	--	1	--	µA
$V_O$	Maximal Voltage Applied to any PIN in High-Impedance State		--	--	VDD+0.3	V
$V_{IH}$	HIGH-Level Input Voltage	Low-Level Logic Input	1.25	--	VDD+0.3	V
$V_{IL}$	LOW-Level Input Voltage	Low-Level Logic Input	GND-0.3	--	0.5	V
$V_{OH}$	HIGH-Level Output Voltage (Note 1)	Push-Pull 2X, $I_{OH}=100\mu A$ at VDD=2.5V	2.443	--	--	V
		Push-Pull 2X, $I_{OH}=3mA$ at VDD=3.3V	3.165	--	--	V
		Push-Pull 2X, $I_{OH}=5mA$ at VDD=5.0V	4.821	--	--	V
$V_{OL}$	LOW-Level Output Voltage (Note 1)	Push-Pull 2X, $I_{OL}=100\mu A$ , at VDD=2.5V	--	--	0.043	V
		Push-Pull 2X, $I_{OL}=3mA$ , at VDD=3.3V	--	--	0.107	V
		Push-Pull 2X, $I_{OL}=5mA$ , at VDD=5.0V	--	--	0.145	V
$I_{OH}$	HIGH-Level Output Current (Note 1)	Push-Pull 2X, $V_{OH}=V_{DD}-0.2V$ at VDD=2.5V	3.40	--	--	mA
		Push-Pull 2X, $V_{OH}=2.4V$ at VDD=3.3V	16.54	--	--	mA

		Push-Pull 2X, V <sub>OH</sub> =2.4V at V <sub>DD</sub> =5.0V	48.49	--	--	mA
I <sub>OL</sub>	LOW-Level Output Current (Note 1)	Push-Pull 2X, V <sub>OL</sub> =0.15V, at V <sub>DD</sub> =2.5V	3.44	--	--	mA
		Push-Pull 2X, V <sub>OL</sub> =0.4V, at V <sub>DD</sub> =3.3V	10.73	--	--	mA
		Push-Pull 2X, V <sub>OL</sub> =0.4V, at V <sub>DD</sub> =5.0V	13.52	--	--	mA
T <sub>SU</sub>	Startup Time	From V <sub>DD</sub> rising past P <sub>ON</sub> <sub>THR</sub>	--	1.66	2.59	ms
P <sub>ON</sub> <sub>THR</sub>	Power On Threshold	V <sub>DD</sub> Level Required to Start Up the Chip	1.60	1.85	2.07	V
P <sub>OFF</sub> <sub>THR</sub>	Power Off Threshold	V <sub>DD</sub> Level Required to Switch Off the Chip	0.97	1.23	1.46	V

**Note:**

1. PINs 1 to 10 are powered from V<sub>DD</sub> and PINs 12 to 20 are powered from V<sub>DD</sub>2.
2. Guaranteed by Design.

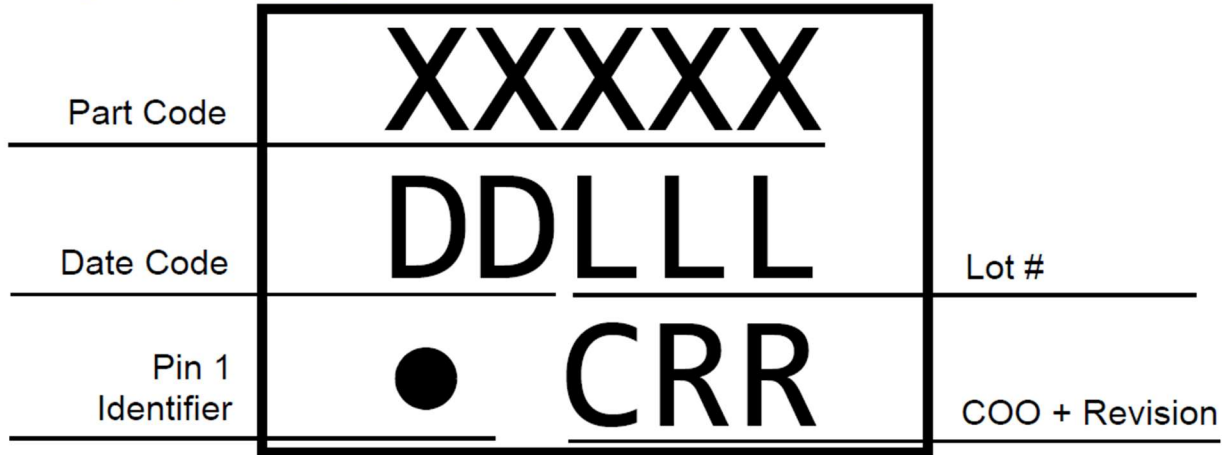
## I<sup>2</sup>C Specifications

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
F <sub>SCL</sub>	Clock Frequency, SCL	V <sub>DD</sub> = (2.3...5.5) V	--	--	400	kHz
t <sub>LOW</sub>	Clock Pulse Width Low	V <sub>DD</sub> = (2.3...5.5) V	1300	--	--	ns
t <sub>HIGH</sub>	Clock Pulse Width High	V <sub>DD</sub> = (2.3...5.5) V	600	--	--	ns
t <sub>i</sub>	Input Filter Spike Suppression (SCL, SDA)	V <sub>DD</sub> = (2.3...5.5) V	--	--	95	ns
t <sub>AA</sub>	Clock Low to Data Out Valid	V <sub>DD</sub> = (2.3...5.5) V	--	--	900	ns
t <sub>BUF</sub>	Bus Free Time between Stop and Start	V <sub>DD</sub> = (2.3...5.5) V	1300	--	--	ns
t <sub>HD_STA</sub>	Start Hold Time	V <sub>DD</sub> = (2.3...5.5) V	600	--	--	ns
t <sub>SU_STA</sub>	Start Set-up Time	V <sub>DD</sub> = (2.3...5.5) V	600	--	--	ns
t <sub>HD_DAT</sub>	Data Hold Time	V <sub>DD</sub> = (2.3...5.5) V	0	--	--	ns
t <sub>SU_DAT</sub>	Data Set-up Time	V <sub>DD</sub> = (2.3...5.5) V	100	--	--	ns
t <sub>R</sub>	Inputs Rise Time	V <sub>DD</sub> = (2.3...5.5) V	--	--	300	ns
t <sub>F</sub>	Inputs Fall Time	V <sub>DD</sub> = (2.3...5.5) V	--	--	300	ns
t <sub>SU_STO</sub>	Stop Set-up Time	V <sub>DD</sub> = (2.3...5.5) V	600	--	--	ns
t <sub>DH</sub>	Data Out Hold Time	V <sub>DD</sub> = (2.3...5.5) V	50	--	--	ns

## Chip address

HEX	BIN	DEC
0x78	1111000	120

## Package Top Marking



- XXXXX - Part ID FieldL identifies the specific device configuration
- DD - Date Code Field: Coded date of manufacture
- LL - Lot Code: Designates Lot #
- C - Assembly Site/COO: Specifies Assembly Site/Country of Origin
- RR - Revision Code: Device Revision

Datasheet Revision	Programming Code Number	Lock Status	Checksum	Part Code	Revision	Date
0.10	001	U	0xD4DC1347			03/06/2023

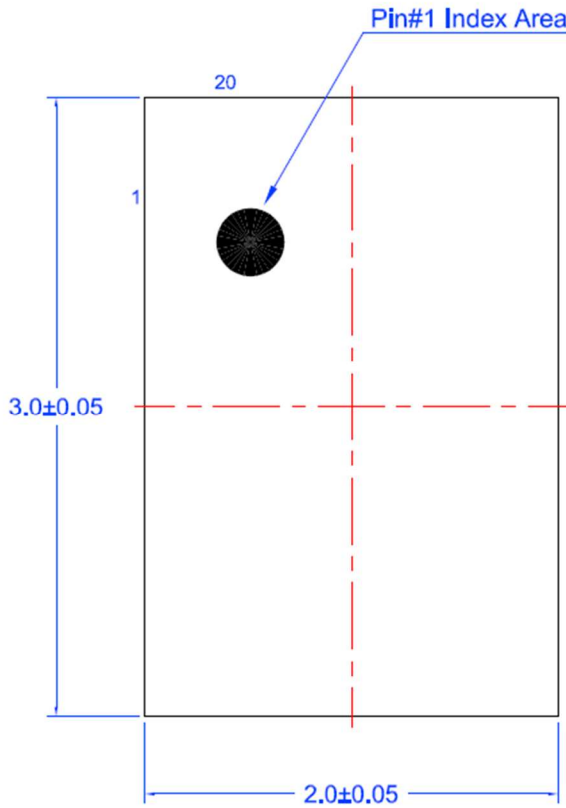
Lock coverage for this part is indicated by , from one of the following options:

<input checked="" type="checkbox"/>	Unlocked
<input type="checkbox"/>	Partly lock read
<input type="checkbox"/>	Partly lock write
<input type="checkbox"/>	Partly lock read and write
<input type="checkbox"/>	Partly lock read and lock write
<input type="checkbox"/>	Lock read and partly lock write
<input type="checkbox"/>	Read lock
<input type="checkbox"/>	Write lock
<input type="checkbox"/>	Lock read and write

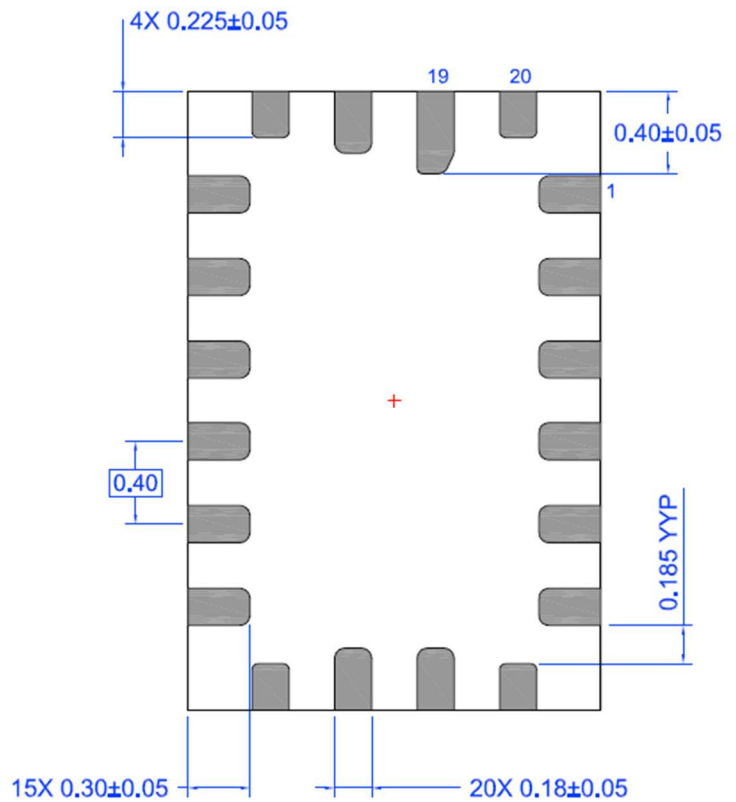
The IC security bit is locked/set for code security for production unless otherwise specified. The Programming Code Number is not changed based on the choice of locked vs. unlocked status.

#### Package Outlines

STQFN 20L 2x3mm 0.4P FCD Package  
 IC Net Weight: 0.008 g



**Marking View**



**BTM View**



**Side View**

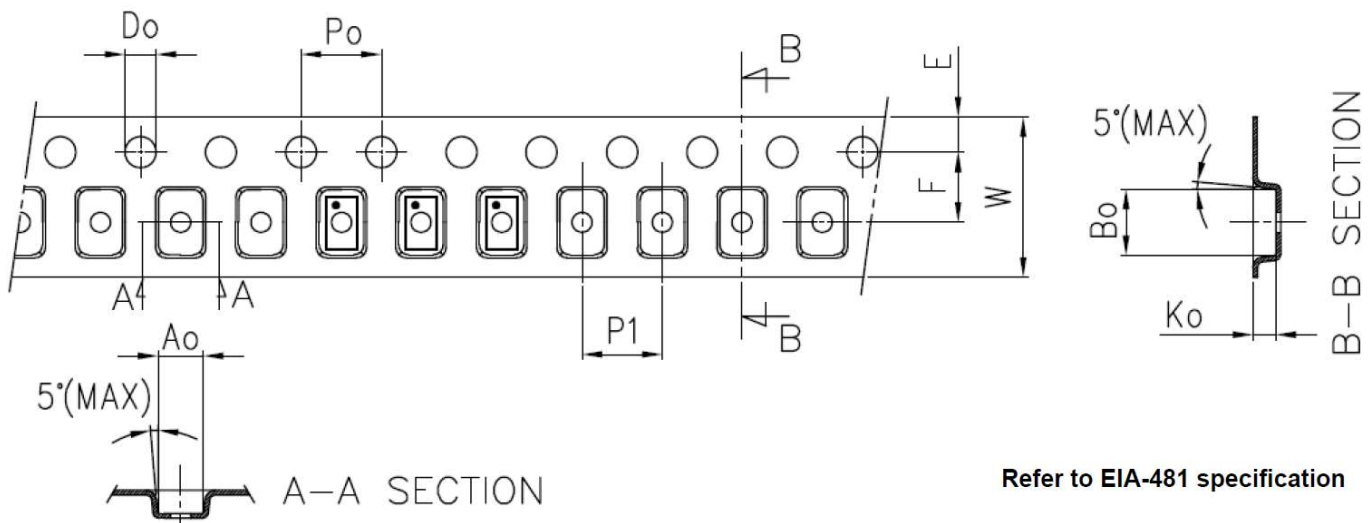
Unit: mm

### Tape and Reel Specification

Package Type	# of Pins	Nominal Package Size [mm]	Max Units		Reel & Hub Size [mm]	Leader (min)		Trailer (min)		Tape Width [mm]	Part Pitch [mm]
			per Reel	per Box		Pockets	Length [mm]	Pockets	Length [mm]		
STQFN 20L 2x3mm 0.4P FCD	20	2 x 3 x 0.55	3000	3000	178 / 60	100	400	100	400	8	4

### Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width
	A0	B0	K0	P0	P1	D0	E	F	W
STQFN 20L 2x3mm 0.4P FCD	2.2	3.15	0.76	4	4	1.5	1.75	3.5	8



### Recommended Reflow Soldering Profile

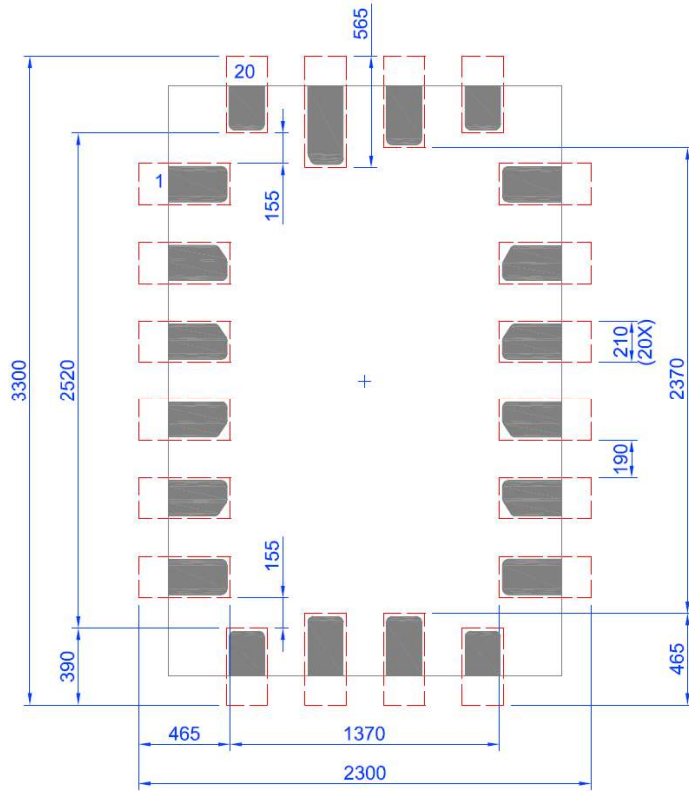
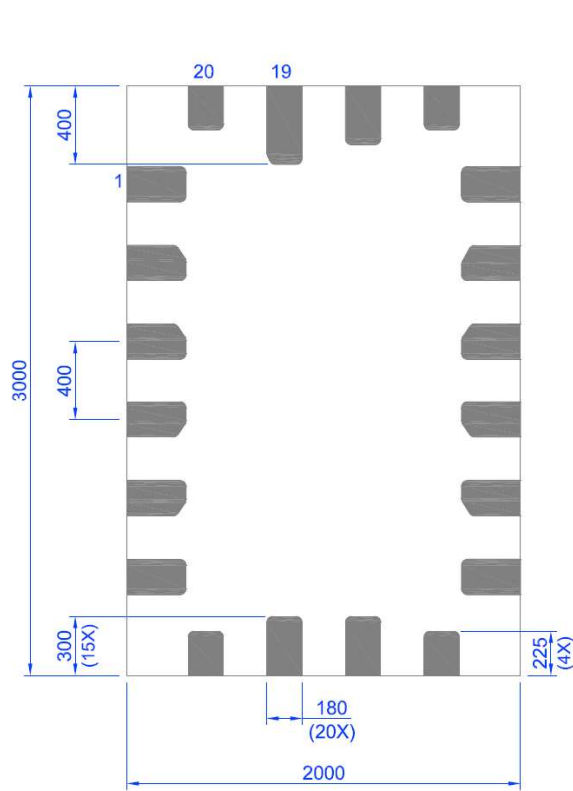
Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.30 mm<sup>3</sup> (nominal). More information can be found at [www.jedec.org](http://www.jedec.org).



### Layout Guidelines

 Exposed Pad  
(PKG face down)

 Recommended Land Pattern  
(PKG face down)



Unit: μm

**Datasheet Revision History**

Date	Version	Change
03/06/2023	0.10	New design for SLG46826 chip

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